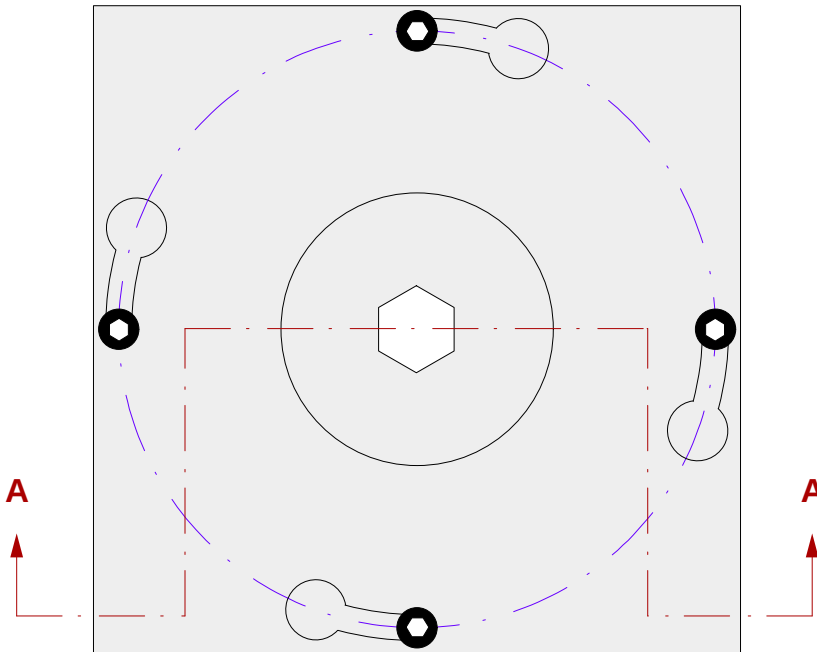


GHz BGA Socket - Direct mount, solderless

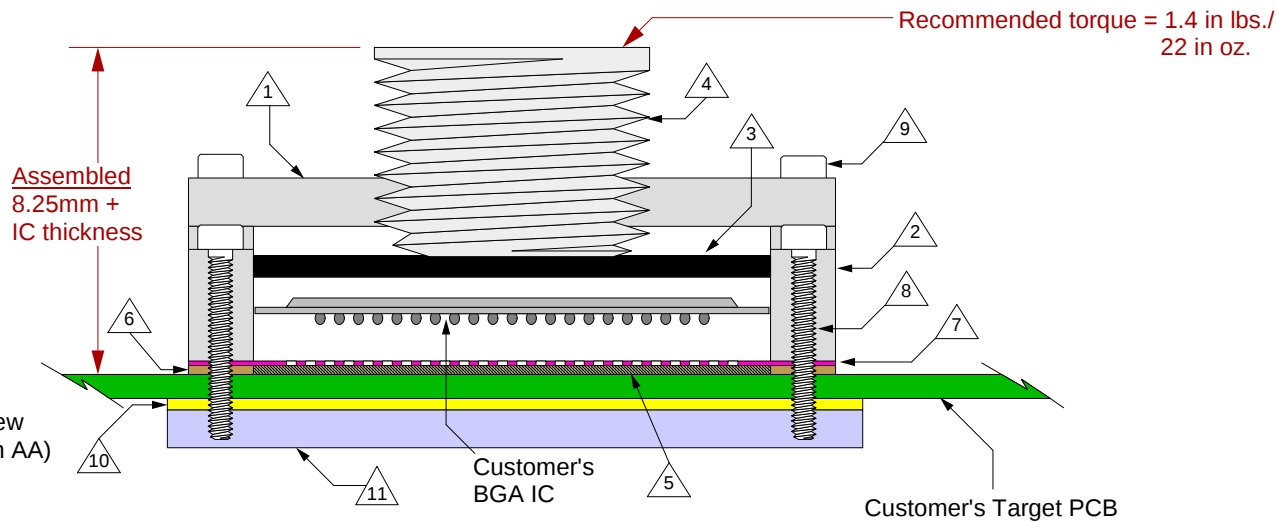
Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid

Top View



Side View
(Section AA)



- 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- 6 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- 11 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

SG-BGA-7033 Drawing

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11351 Rupp Drive, Suite 400, Burnsville, MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: B

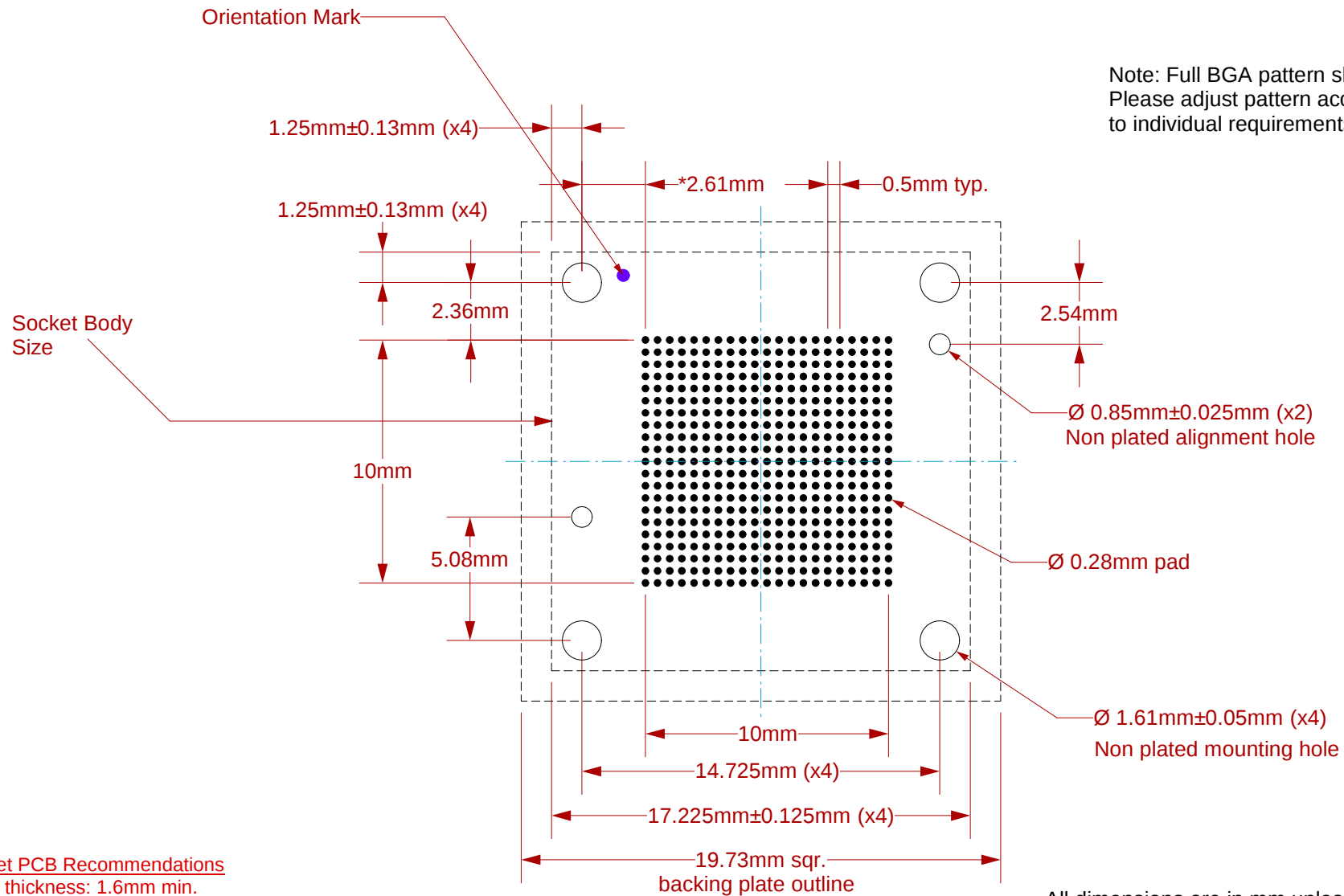
Drawing: H. Hansen

Date: 1/24/05

File: SG-BGA-7033 Dwg

Modified: 6/12/09, AE

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.



Note: Full BGA pattern shown.
Please adjust pattern according to individual requirements.

Target PCB Recommendations

Total thickness: 1.6mm min.

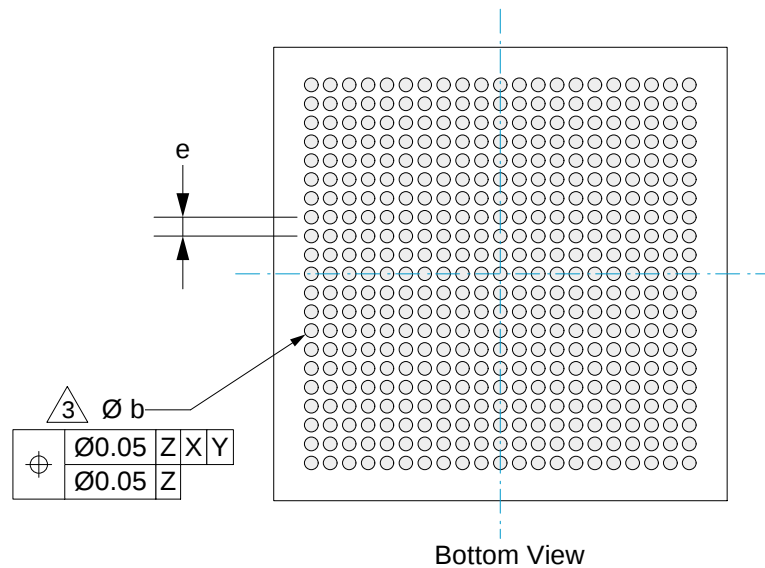
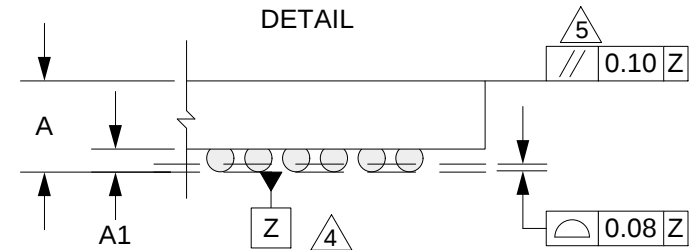
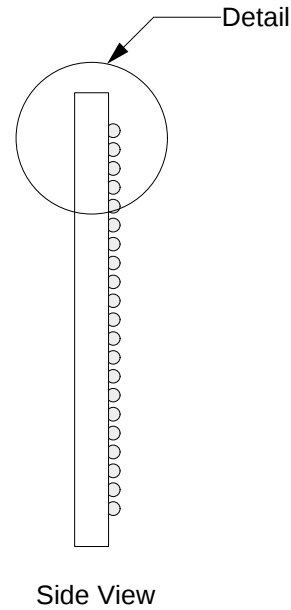
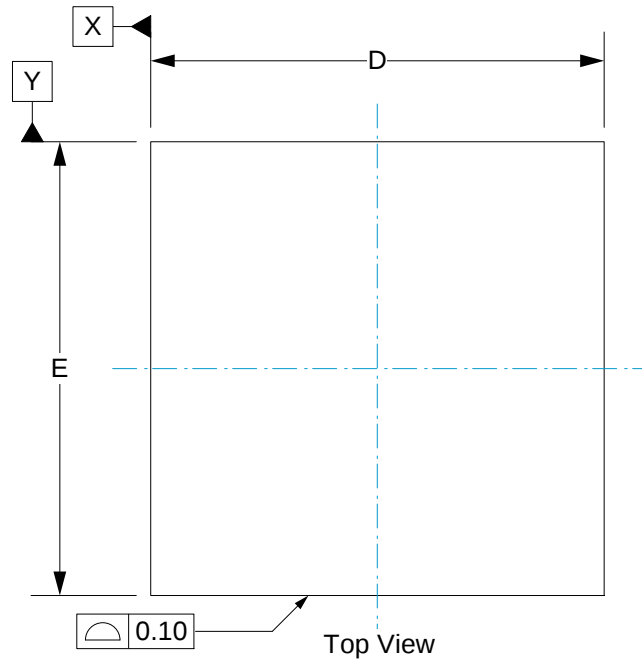
Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

SG-BGA-7033 Drawing	Status: Released	Scale: 4:1	Rev: B
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	File: SG-BGA-7033 Dwg	Modified: 6/12/09, AE	



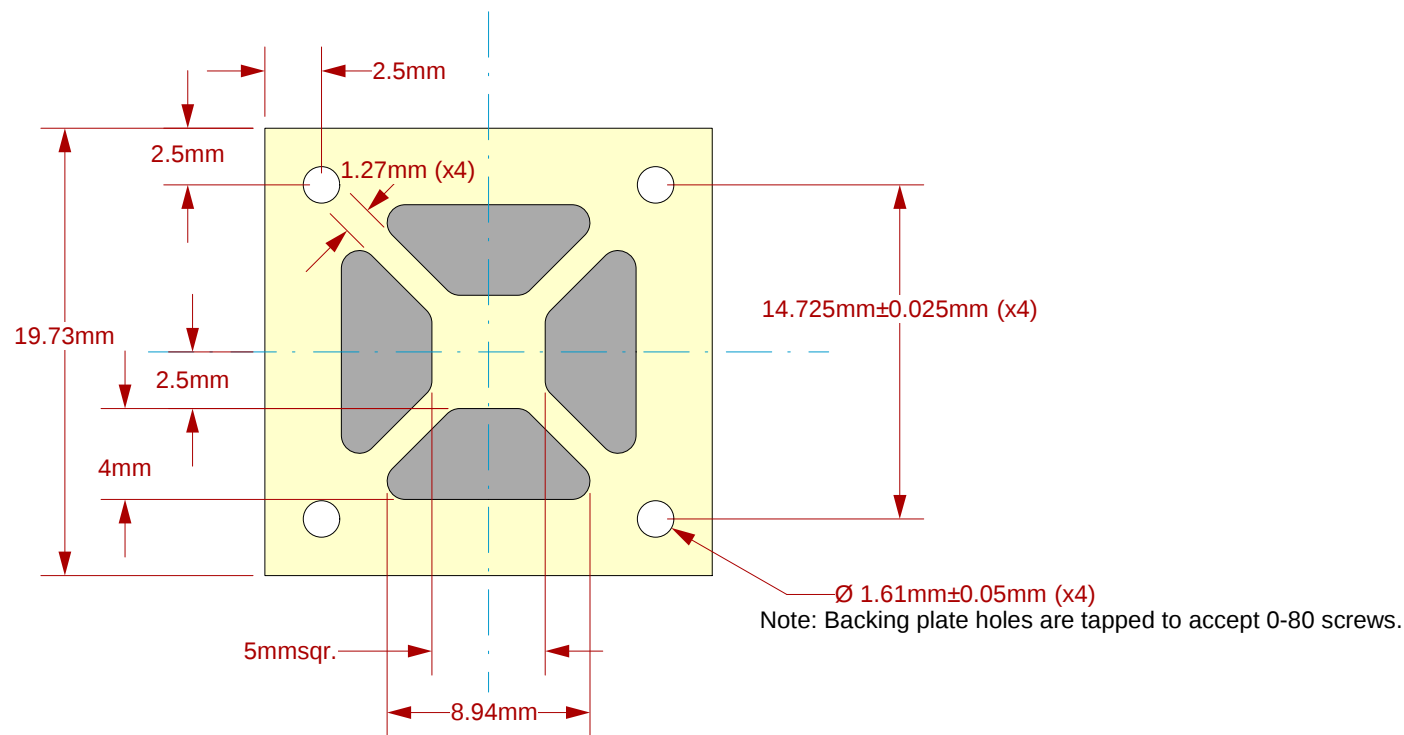
1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.2
A1	0.2	0.3
b		0.36
D	12.0 BSC	
E	12.0 BSC	
e	0.5 BSC	

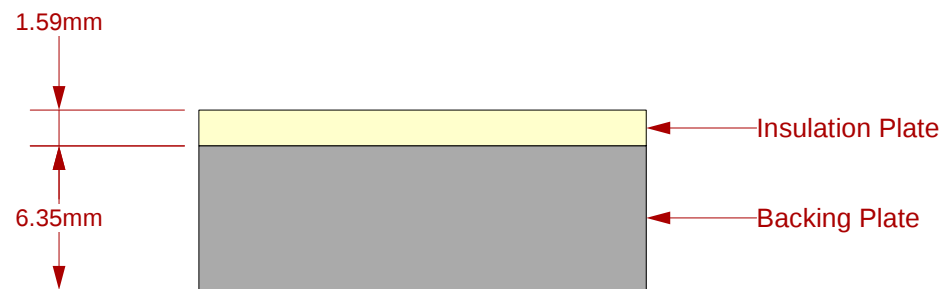
21 x 21 array

	SG-BGA-7033 Drawing		Status: Released	Scale: 1:0.2	Rev: B
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com		Drawing: H. Hansen		Date: 1/24/05
			File: SG-BGA-7033 Dwg		Modified: 6/12/09, AE

Top View



Side View



Description: Insulation Plate and Backing Plate

SG-BGA-7033 Drawing	Status: Released	Scale: 3:1	Rev: B
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	File: SG-BGA-7033 Dwg	Modified: 6/12/09, AE	

All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)